We claim:

1. A method of fabricating SWNT probes for use in atomic force microscopy,

growing SWNTs on a substrate using chemical vapor deposition;

imaging said substrate using an atomic force microscope comprising a tip; and attaching one of said SWNTs to said tip, thereby producing a tip bearing a

SWAT,

- 2. The method of claim 1 wherein the SWNTs are deposited normal to the surface of said substrate.
- 3. The method of claim 2 wherein the substrate is a silicon wafer.
- 4. The method of claim 3 wherein growing the SWNTs on a silicon wafer comprises the steps of:

depositing on said wafer a metallic catalytic material;

placing said silicon wafer in a CVD furnace; and

exposing said silicon wafers to a gaseous atmosphere comprising a carbon containing gas.

- 5. The method of claim 4 wherein the metallic catalytic material is selected from the group consisting of metals, metal oxides, metallic salts, and metallic particles.
- 6. The method of claim 4 wherein the metallic catalytic material is in solution.
- 7. The method of claim 6 wherein the metallic catalytic material is selected from the group consisting of ferric salts, nickel salts, cobalt salts, platinum salts, molybdenum salts, and ruthenium salts.

- 21 -

- 8. The method of claim 7 wherein the metallic catalytic material is ferric nitrate.
- 9. The method of claim 6 wherein the solution comprises an alcohol.

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- 10. The method of claim 9 wherein the alcohol is selected from the group consisting of methanol, ethanol, and isopropanol.
- 11. The method of claim 10 wherein the alcohol is isopropanol.
- 12. The method of claim 4 wherein the carbon containing gas is ethylene.
- 13. The method of claim 9 wherein the carbon containing gas is ethylene, the metallic catalytic material is ferric nitrate, and the alcohol is isopropanol.
- 14. The method of claim 1 wherein imaging said substrate further comprises applying a pulsed electric field.
- 15. The method of claim 3 wherein growing the SWNTs on a silicon wafer comprises the steps of:

treating said silicon wafer with metallic colloid particles;

placing said silicon wafer in a CVD furnace; and

exposing said silicon wafers to a gaseous atmosphere comprising a carbon containing gas.

- 16. The method of claim 15 wherein the metallic colloid is selected from the group consisting of iron colloids, nickel colloids, cobalt colloids, platinum colloids, molybdenum colloids, and ruthenium colloids.
- 17. The method of claim 16 wherein the metallic colloid is an iron colloid.
- 18. The method of claim 15 wherein the carbon containing gas is ethylene.
- 19. The method of claim 15 wherein the metallic colloids have diameters of about 3-15 nm.
- 20. The method of claim 1 wherein the SWNT has a diameter from about 2 nm to about 13 nm.
- 21. The method of claim 1 wherein the SWNT has a diameter from about 2 nm to about 9 nm.
- 22. The method of claim 1 wherein the SWNT has a diameter from about 3 nm to about 5 nm.
- 23. The method of claim 1 wherein said tip bears an adhesive.

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- 24. The method of claim 1 further comprising the step of heating said tip bearing a SWNT.
- 25. The method of claim 1 further comprising the step of treating the tip bearing a SWNT with an electromagnetic field.
- 26. A method of growing carbon nanotubes comprising the steps of:

providing a substrate;

treating said substrate with a metallic colloid solution;

placing said substrate in a CVD furnace; and

exposing said substrate to a gaseous atmosphere comprising a carbon containing gas, thereby growing a carbon nanotube on said substrate.

- 27. The method of claim 26, wherein said carbon nanotube is a SWNT.
- 28. The method of claim 26, wherein said carbon nanotube is a MWNT.
- 29. The method of claim 26, wherein said substrate is a silicon wafer.
- 30. The method of claim 26 wherein the metallic colloid is selected from the group consisting of iron colloids, nickel colloids, cobalt colloids, platinum colloids, molybdenum colloids and ruthenium colloids.
- 31. The method of claim 30 wherein the metallic colloid is an iron colloid.
- 32. The method of claim 26 wherein the carbon containing gas is ethylene.
- 33. The method of claim 31 wherein the carbon containing gas is ethylene.
- 34. The method of claim 26 wherein the metallic colloids have diameters of about 3-15 nm.
- 35. The method of claim 26 wherein the solution comprises an organic solvent.
- 36. The method of claim 35 wherein the solution comprises toluene.